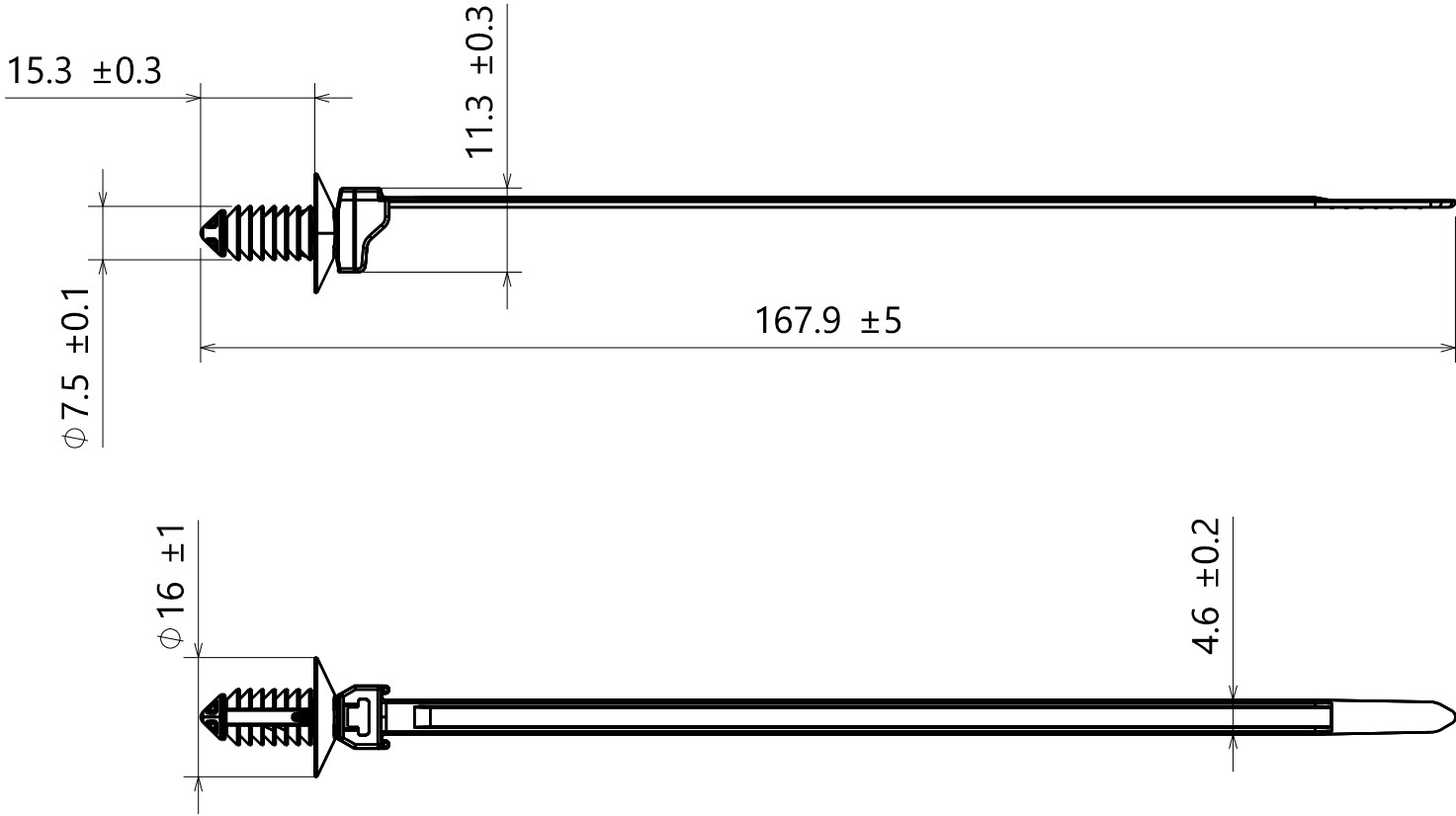
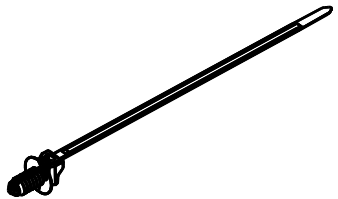
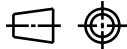




Product Type 产品型号	Hole Size 适用孔径	Bundle Dia 捆绑直径	Panel Thickness 适用板厚	Material 材料
T50SOSFT6.5LG-E4	Ø6.5±0.4mm 6.35±0.25mm HEX	1.0-35.0mm	0.6-8.25mm	PA66HIRHSB ①
				PA46-GY ②
				PA66HS-GY ③



Revision Level			Revision Record			The copyright of this drawing is reserved by HellermannTyton.		Drawn	Date (YYYY/MM/DD)	Title T50SOSFT6.5LG-E4		Scale 1:1 Global Project Number 16-1353	
Drawing	State	Part	Add material PA66HS-GY			Lance.Lv	2018/11/05						
03.1	Design Release					Approved	Date (YYYY/MM/DD)						
						Kevin.Tang	2018/11/05						
						All drawing revisions are stored in CAD PDM database							
Changed		Date (YYYY/MM/DD)		Units mm HellermannTyton www.HellermannTyton.com		Drawing-No 16-1353-021-CSC		Format A4 Sheet 1 / 1					
Lance.Lv		2021/08/11											
Approved		Date (YYYY/MM/DD)											
Roger.Chang		2021/08/11											
6			5		4		3		2		1		